



IIT Bombay Nanofabrication Facility

Tool Name: Sputter (ATC 2200)

Glimpse

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Photograph



It is a sputtering tool with the capability to co-sputter multiple material to obtain film with composition gradient on the depositing substrate

Location - Nano Lab

Process Capabilities

1. Co- Sputter 4 materials at a time.
2. Deposition at elevated temperatures.
3. Substrate to target distance variation possible.
4. Angle of the gun can be varied.

Specifications

1. No. of guns (targets) in the chamber – 7
2. No. of RF sources – 3 (Max. 300 W)
3. No. of DC sources – 1 (Max 750 W)
4. No. of guns that can be used at the same time – 4 (3 RF & 1 DC)
5. Max. substrate temperature – 600 °C
6. Base Vacuum – 8×10^{-8} mTorr
7. Deposition uniformity – 2 %
8. Gases allowed – Ar, N₂

Target material, allowed substrates & materials

http://www.iitbnf.iitb.ac.in/iitbnf/infrastructure/equipment_details.php?machid=196